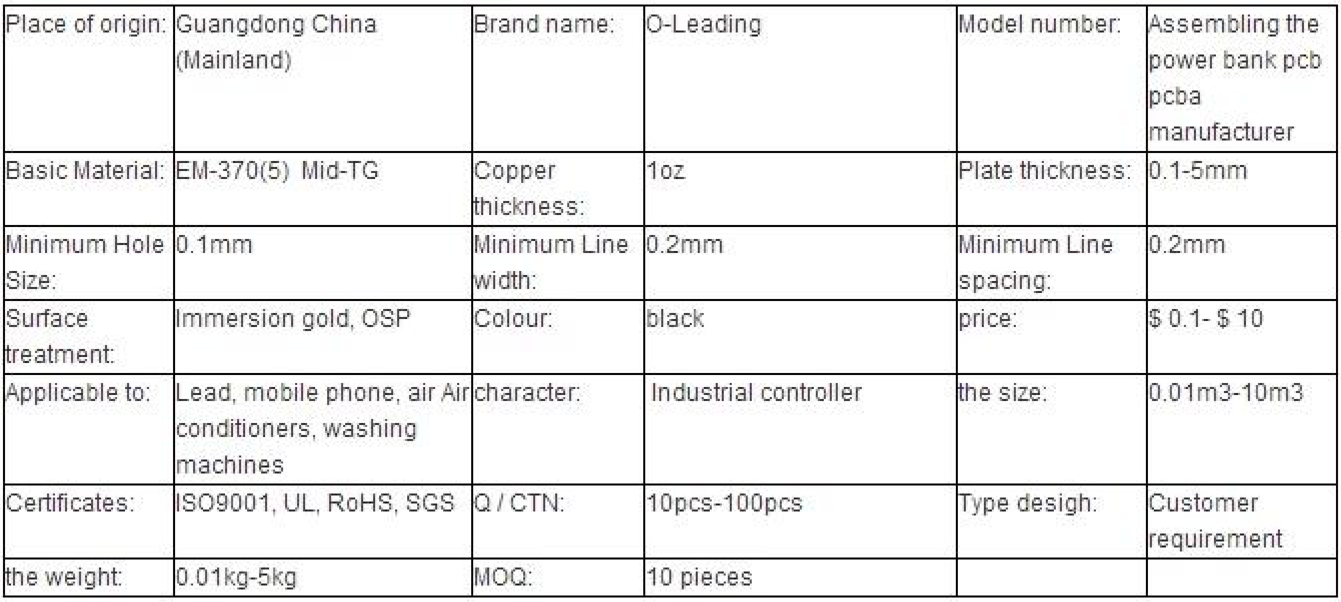
Fori di rame piastra minima .025 AVG,. 020 min.. I fori non possono essere collegati
Imballi con la pellicola trasparente incolore della bolla, 25 pc/sacchetto, disseccante messo nel fianco, metta la scheda dell'indicatore di umidità sul lato superiore

fornitore: PCB design in Cina, PCB Produttore in Cina, Piccolo volume PCB Produttore

Descrizione del prodotto:
informazioni brevi



Place of origin:	Guangdong China (Mainland)	Brand name:	O-Leading	Model number:	Assembling the power bank pcb pcba manufacturer
Basic Material:	EM-370(5) Mid-TG	Copper thickness:	1oz	Plate thickness:	0.1-5mm
Minimum Hole Size:	0.1mm	Minimum Line width:	0.2mm	Minimum Line spacing:	0.2mm
Surface treatment:	Immersion gold, OSP	Colour:	black	price:	$ 0.1- $ 10
Applicable to:	Lead, mobile phone, air Air conditioners, washing machines	character:	Industrial controller	the size:	0.01m3-10m3
Certificates:	ISO9001, UL, RoHS, SGS	Q / CTN:	10pcs-100pcs	Type desigh:	Customer requirement
the weight:	0.01kg-5kg	MOQ:	10 pieces		

Packing & Delivery

Packaging Details:	16-year-old professional OEM client Board Manufacturer
Delivery detail:	7-12days.

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paragraph	2017		2018 ~ 2020		2021 ~ 2023	
	Amount	Sample	Amount	Sample	Amount	Sample
Number of layers	32	42	38	44	42	48
Min. Line / Spacing (μm)	50/50	40/45	40/45	40/40	35/40	35/35
Min. Drilling hole Diameter (mm)	0,15	0.10	0,15	0.10	0,15	0.10
Aspect Ratio PTH	14: 1	16: 1	16: 1	18: 1	18: 1	20: 1
N + C + N,	4 + C + 4	5 + C + 5	5 + C + 5	6 + C + 6	5 + C + 5	6 + C + 6
Any layer Relationship	5 + 2 + 5	6 + 2 + 6	5 + 2 + 5	6 + 2 + 6	5 + 2 + 5	6 + 2 + 6
Filling of plates through	YES	-	YES	-	YES	-
Minimum Core Thickness (Excluding copper) (μm)	50	40	40	thirty	40	thirty
Minimum Laser Drill Diameter (μm)	75	65	65	50	50	40
Via at the Funeral Hole / styling through	YES	-	YES	-	YES	-
material	FR4, Megtron, Nelco, Rogers, Heavy Copper, etc.					
Built-in capacitor printed circuit board	YES	-	YES	-	YES	-
Surface process	Lead-free HASL, ENIG, OSP, silver with immersion, tin of immersion, Flash of gold, Golden finger coating, Selective solid gold coating, Flaking solder mask, carbon ink					